

## 1000V High Voltage Monitor IC

### ■ FEATURES

- AEC-Q100 Grade 1
- Operation Voltage Range 2.2V to 5.5V
- Common Mode Input Voltage Range 1000V
- Differential Input Voltage  $\pm 1000V$
- High Precision Attenuation Rate  
 $\pm 1\%$  ( $T_a = -40^\circ C$  to  $125^\circ C$ )
- High Input Resistance 30M $\Omega$  min.
- Integrated EMI filter
- Operating Temperature  $-40^\circ C$  to  $125^\circ C$
- Package PMAP11-PM  
New Package for Creepage Distance (IEC/EN60664)

### ■ GENERAL DESCRIPTION

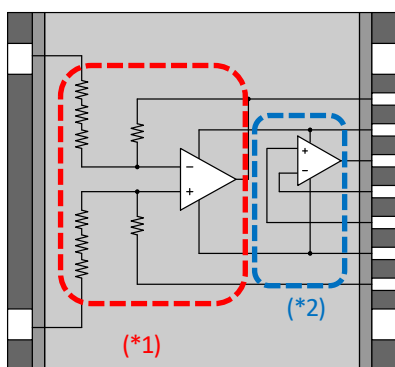
The NJU7890 is a high voltage monitor IC capable of inputting voltages up to 1000V. With our proprietary semiconductor process technology, NJU7890 realizes wide common mode / differential input voltage.

The NJU7890 is suitable for powertrain application such as HV and EV.

### ■ APPLICATION

- Automotive application  
Powertrain and Battery management ECU
- High-Voltage Monitoring Applications

### ■ BLOCK DIAGRAM



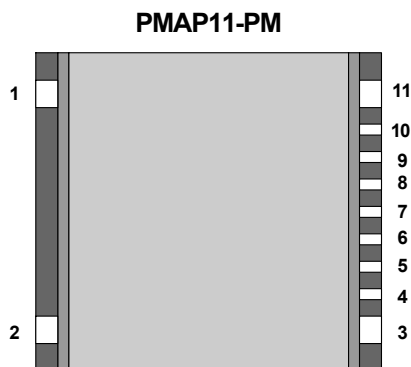
(\*1) High Voltage Monitor Block

(\*2) OP-Amp Block

■ ATTENUATION RATE VERSION

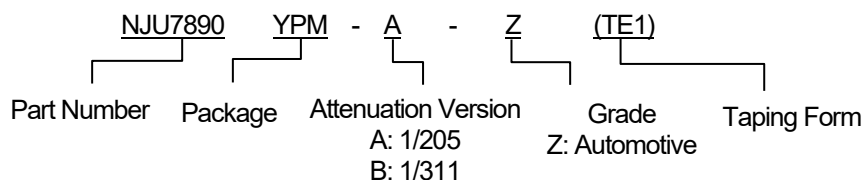
PRODUCT NAME	INPUT RESISTANCE	ATTENUATION VERSION	GAIN	PACKAGE
NJU7890YPM-A-Z	30MΩ	A	1/205	PMAP11-PM
NJU7890YPM-B-Z	30MΩ	B	1/311	PMAP11-PM

■ PIN CONFIGURATION



PIN NO.	SYMBOL
1	-HVIN
2	+HVIN
3	V <sup>-</sup>
4	REF
5	V <sup>-</sup>
6	+OPIN
7	-OPIN
8	OP OUT
9	V <sup>+</sup>
10	OUT
11	V <sup>-</sup>

■ PRODUCT NAME INFORMATION



■ ORDERING INFORMATION

PRODUCT NAME	PACKAGE	RoHS	HALOGEN-FREE	TERMINAL FINISH	MARKING	WEIGHT (mg)	MOQ (pcs)
NJU7890YPM-A-Z (TE1)	PMAP11-PM	Yes	Yes	Sn2Bi	90AZ	300	2000
NJU7890YPM-B-Z (TE1)	PMAP11-PM	Yes	Yes	Sn2Bi	90BZ	300	2000

■ ABSOLUTE MAXIMUM RATINGS (REF = 0V, unless otherwise noted.)

PARAMETER	SYMBOL	RATINGS	UNIT
<b>GENERAL CHARACTERISTICS</b>			
Supply Voltage	$V^+ - V^-$	7	V
Power Dissipation ( $T_a = 25^\circ\text{C}$ ) PMAP11-PM	$P_D$	2Layers / 4Layers 1100 <sup>(1)</sup> / 2000 <sup>(2)</sup>	mW
Junction Temperature	$T_j$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55 to 150	$^\circ\text{C}$
<b>HIGH VOLTAGE MONITOR</b>			
Input Voltage 1	$V_{IN1}$	-1000 to 1000	V
Differential Input Voltage 1	$V_{ID1}$	$\pm 1000$ <sup>(3)</sup>	V
Reference Voltage	REF	$V^- - 0.3$ to $V^+$	V
<b>OPERATIONAL AMPLIFIER</b>			
Input Voltage 2	$V_{IN2}$	$V^- - 0.3$ to $V^+$	V
Differential Input Voltage 2	$V_{ID2}$	$\pm 7$	V

(1) 2-Layer: Mounted on glass epoxy board (76.2 mm × 114.3 mm × 1.6 mm: based on EIA/JEDEC standard, 2-layer FR-4).

(2) 4-Layer: Mounted on glass epoxy board (76.2 mm × 114.3 mm × 1.6 mm: based on EIA/JEDEC standard, 4-layer FR-4), internal Cu area: 74.2 mm × 74.2 mm.

(3) Differential voltage is the voltage difference between +HVIN and -HVIN

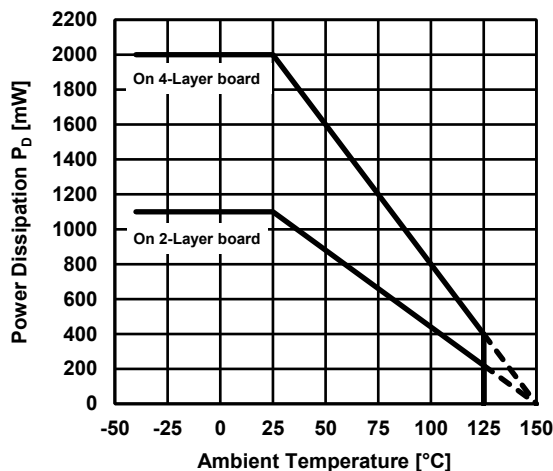
■ RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	RATINGS	UNIT
Supply Voltage	$V^+ - V^-$	2.2 to 5.5	V
Reference Voltage	REF	$V^-$ to $V^+ - 0.85$	V
Operating Temperature	$T_{opr}$	-40 to 125	$^\circ\text{C}$

■ POWER DISSIPATION vs. AMBIENT TEMPERATURE

PMP11-PM Power Dissipation vs. Temperature

$T_{opr} = -40^\circ\text{C}$  to  $125^\circ\text{C}$ ,  $T_j = 150^\circ\text{C}$



## ■ ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
<b>GENERAL CHARACTERISTICS</b> ( $V^+ = 5V$ , $V^- = 0V$ , $T_a = 25^\circ\text{C}$ , unless otherwise noted.)							
Supply Current	$I_{\text{SUPPLY}}$	No signal	-	1.2	1.8	mA	
		No signal, $T_a = -40^\circ\text{C}$ to $125^\circ\text{C}$	-	-	1.8		
<b>HIGH VOLTAGE MONITOR</b> ( $V^+ = 5V$ , $V^- = 0V$ , $\text{REF} = 2.5V$ , $T_a = 25^\circ\text{C}$ , unless otherwise noted.)							
Input Resistance	$R_{\text{IN}}$	$-HV_{\text{IN}}$ to $\text{OUT}$ , $T_a = -40^\circ\text{C}$ to $125^\circ\text{C}$	30	-	42	$\text{M}\Omega$	
		$+HV_{\text{IN}}$ to $\text{REF}$ , $T_a = -40^\circ\text{C}$ to $125^\circ\text{C}$	30	-	42		
Attenuation Rate	ATT	Aver		-0.7%	1/205	+0.7%	V/V
			$T_a = -40^\circ\text{C}$ to $125^\circ\text{C}$	-1.0%	-	+1.0%	
		Bver		-0.7%	1/311	+0.7%	
			$T_a = -40^\circ\text{C}$ to $125^\circ\text{C}$	-1.0%	-	+1.0%	
Output Offset Voltage	$V_{\text{OS-RT0}}$	$-/+HV_{\text{IN}} = 0V$	-	0.04	0.30	mV	
		$-/+HV_{\text{IN}} = 0V$ , $T_a = -40^\circ\text{C}$ to $125^\circ\text{C}$	-	-	0.80		
Supply Voltage Rejection Ratio 1	SVR1	$V^+ = 2.2V$ to $5.5V$ , Referred to output	70	80	-	dB	
Common Mode Rejection Ratio1	CMR1	Aver	$V_{\text{ICM}} = -/+HV_{\text{IN}} = 0V$ to $660V$ , Referred to output, $V^+ = 5V$ , $V^- = 0V$ , $\text{REF} = 0.5V$	85	100	-	dB
		Bver	$V_{\text{ICM}} = -/+HV_{\text{IN}} = 0V$ to $1000V$ , Referred to output, $V^+ = 5V$ , $V^- = 0V$ , $\text{REF} = 0.5V$	85	100	-	
High-level Output Voltage 1	$V_{\text{OH1}}$	$R_L = 10k\Omega$ to $2.5V$	$V^+ - 0.20$	$V^+ - 0.05$	-	V	
Low-level Output Voltage 1	$V_{\text{OL1}}$	$R_L = 10k\Omega$ to $2.5V$	-	$V^+ - 0.05$	$V^+ + 0.20$	V	

■ Calculation of output voltage

$$V_{OUT} = (V_{+HVIN} - V_{-HVIN}) \times ATT + V_{REF} + V_{OS-RTO} + \frac{|5V - V^+|}{SVR1} + \frac{|V_{+HVIN}|}{CMR1}$$

Calculation example

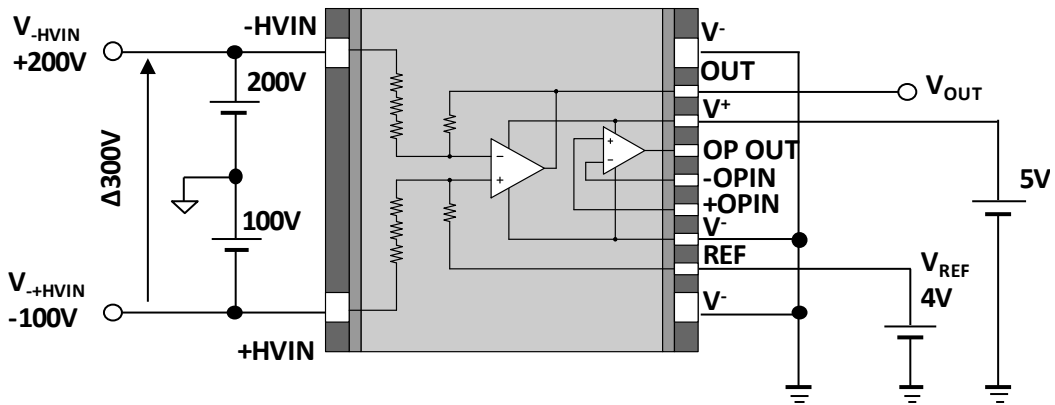
$V_{+HVIN} = -100V, V_{-HVIN} = 200V, V_{REF} = 4V, V^+ = 5.2V, ATT = 1/205 \pm 0.7\% (T_a = 25^\circ C), V_{OS-RTO} = 0.3mV, SVR1 = 70dB, CMR1 = 85dB$

$$V_{OUT} = (-100V - 200V) \times \left(\frac{1}{205} \pm 0.7\%\right) + 4V + 0.3mV + \frac{|-0.2V|}{70dB} + \frac{|-100V|}{85dB}$$

$$V_{OUT} = -300V \times \left(\frac{1}{205} \pm 0.7\%\right) + 4V + 0.3mV + 0.06mV + 5.6mV = 2.553V$$

Without the error component of the calculation example above, the output voltage is 2.537V. The error 0.016V obtained from the calculation example is  $0.016V \times (1 \div ATT) = 3.280V$  by calculating the input conversion. The error rate obtained from the input conversion value can be calculated as 1.09% from  $3.280V \div 300V$ . In addition to the above formula, please be aware that there is a VREF error (accuracy influence).

Evaluation circuit example



■ +HVIN input Voltage Range

In order for this IC to operate normally, the positive input terminal voltage ( $V_{+IN}$ ) of operational amplifier A must be within the common mode input voltage range of operational amplifier A.

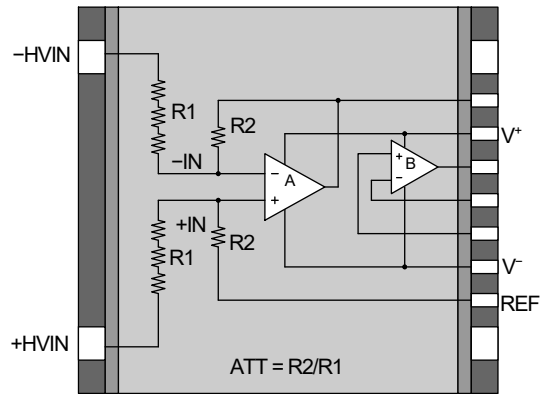
Operational amplifier A: common mode input voltage range

$$V^- \leq V_{+IN} \leq V^+ - 0.85V$$

Therefore, it is necessary to satisfy the following formula expressed by  $V^+/V^-$  (supply voltage),  $V_{+HVIN}$  (+HVIN terminal voltage),  $V_{REF}$  (REF terminal voltage), ATT (attenuation rate).

Calculation

$$V^- \leq \frac{1}{1 + ATT^{-1}} \times V_{+HVIN} + \frac{1}{1 + ATT} \times V_{REF} \leq V^+ - 0.85V$$



Calculation example

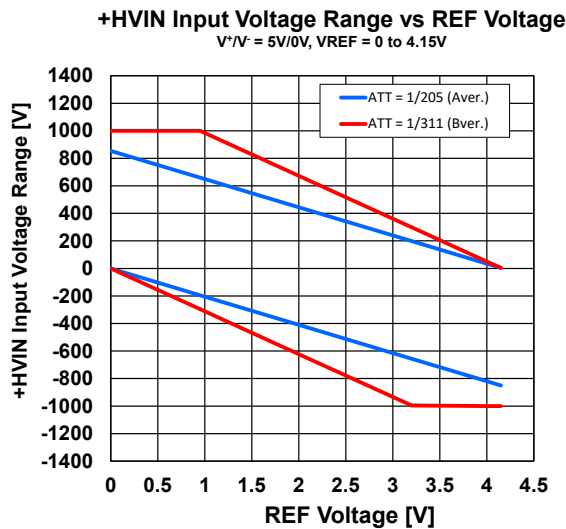
$$V_{REF} = 4V, V^+ / V^- = 5V / 0V, ATT = 1/205$$

$$0V \leq \frac{1}{1 + 205} \times V_{+HVIN} + \frac{1}{1 + 1/205} \times 4V \leq 5V - 0.85V$$

$$-820V \leq V_{+HVIN} \leq 34.9V$$

Characteristics example

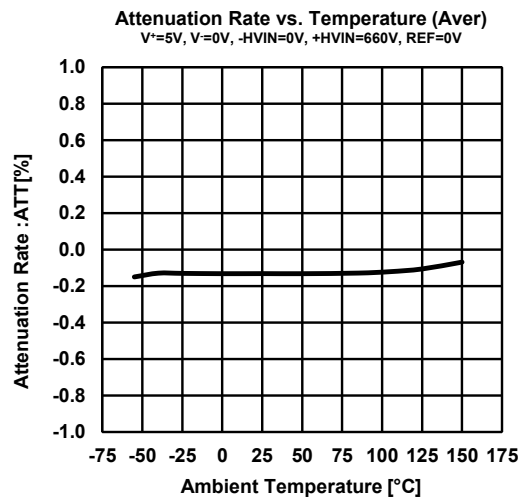
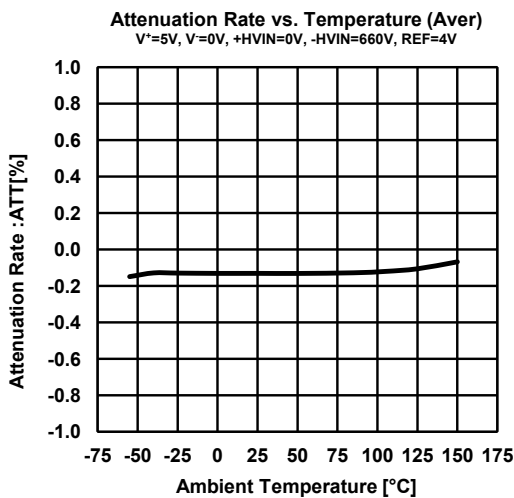
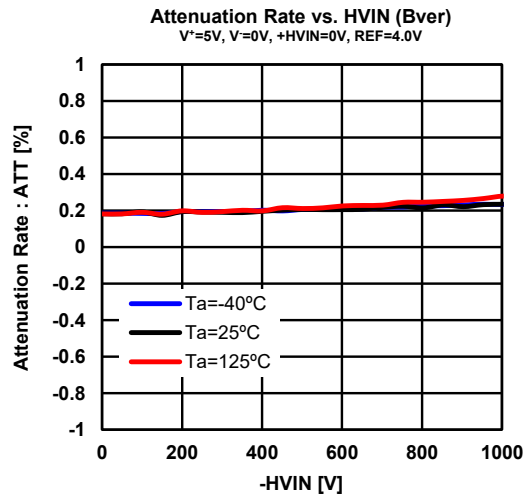
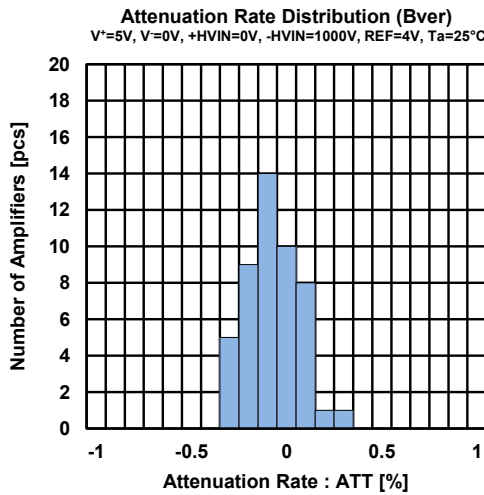
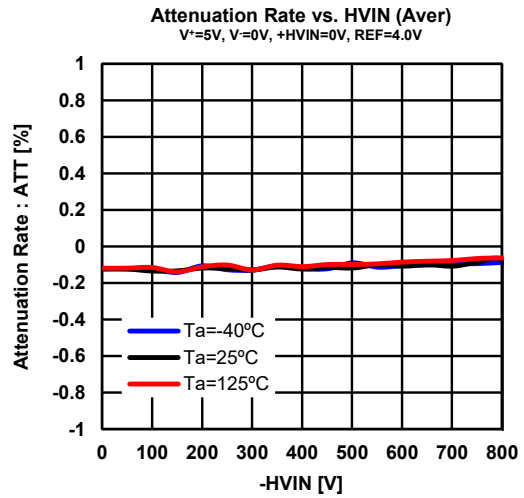
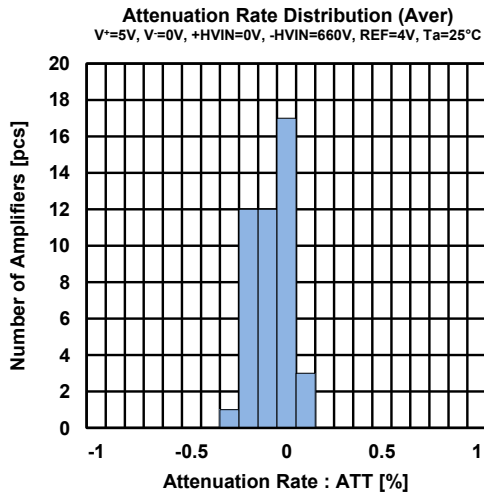
The figure below shows an example of characteristics when the attenuation rate is set to 1/205 (Aver) and 1/311 (Bver). The range indicated by the graph is the input voltage range of the +HVIN.



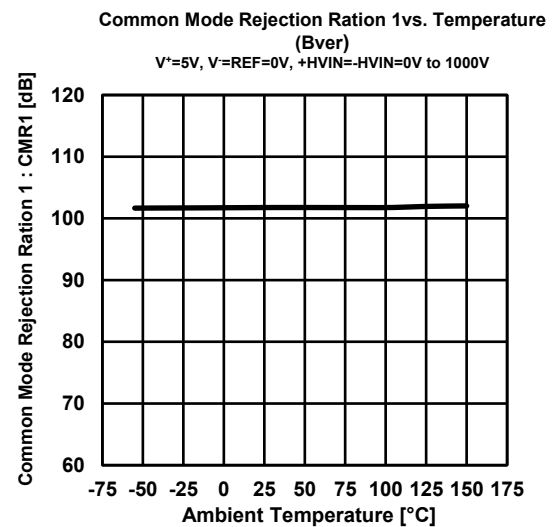
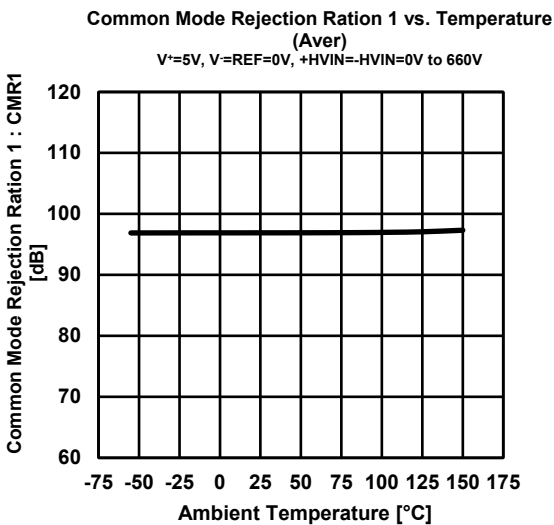
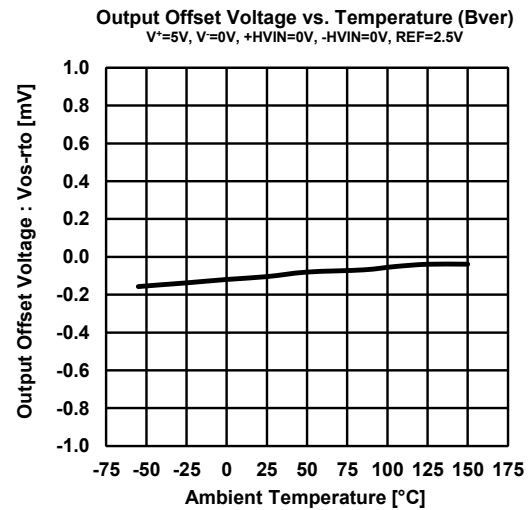
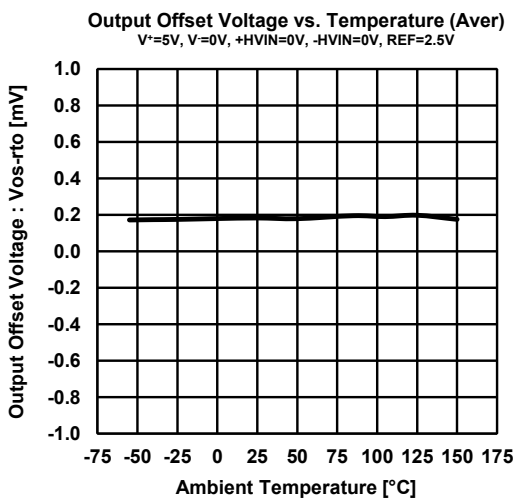
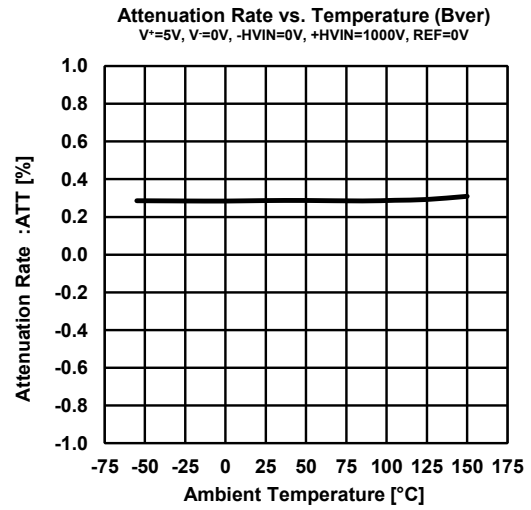
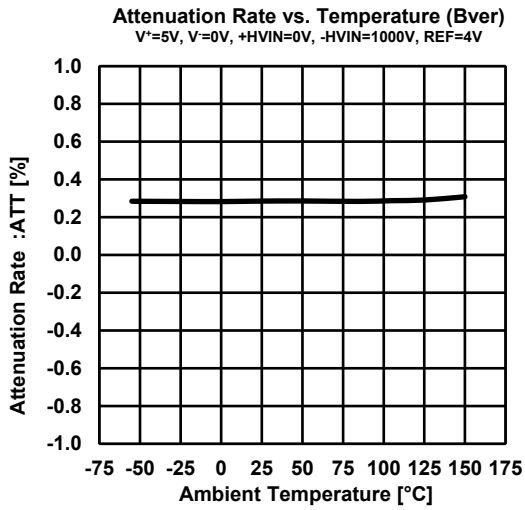
## ■ ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OPERATIONAL AMPLIFIER</b> ( $V^+ = 5V$ , $V^- = 0V$ , $T_a = 25^\circ C$ , unless otherwise noted.)						
Input Offset Voltage	$V_{io}$	$T_a = -40^\circ C$ to $125^\circ C$	-	0.04	0.30	mV
Input Offset Voltage Drift	$\Delta V_{io}/\Delta T$	$T_a = -40^\circ C$ to $125^\circ C$	-	0.5	-	$\mu V/^\circ C$
Input Bias Current	$I_B$	-/+OPIN	-	1	-	pA
Input Offset Current	$I_{io}$	-/+OPIN	-	1	-	pA
Open-Loop Voltage Gain	$A_v$	$R_L \geq 10k\Omega$ to 2.5V, OP OUT = 2.5V $\pm 2V$	100	130	-	dB
		$R_L \geq 10k\Omega$ to 2.5V, OP OUT = 2.5V $\pm 2V$ , $T_a = -40^\circ C$ to $125^\circ C$	100	-	-	
High-level Output Voltage 2	$V_{OH2}$	$R_L = 10k\Omega$ to 2.5V	4.95	4.98	-	V
		$R_L = 10k\Omega$ to 2.5V, $T_a = -40^\circ C$ to $125^\circ C$	4.95	-	-	
Low-level Output Voltage 2	$V_{OL2}$	$R_L = 10k\Omega$ to 2.5V	-	0.02	0.05	V
		$R_L = 10k\Omega$ to 2.5V, $T_a = -40^\circ C$ to $125^\circ C$	-	-	0.05	
High-level Output Voltage 3	$V_{OH3}$	$R_L = 600k\Omega$ to 2.5V	4.85	4.92	-	V
		$R_L = 600k\Omega$ to 2.5V, $T_a = -40^\circ C$ to $125^\circ C$	4.85	-	-	
Low-level Output Voltage 3	$V_{OL3}$	$R_L = 600k\Omega$ to 2.5V	-	0.08	0.15	V
		$R_L = 600k\Omega$ to 2.5V, $T_a = -40^\circ C$ to $125^\circ C$	-	-	0.20	
Output Current	$I_{OUT}$	$V_{OH} \geq 4.85V$ , $V_{OL} \leq 0.15V$	2	3	-	mA
		$V_{OH} \geq 4.85V$ , $V_{OL} \leq 0.15V$ , $T_a = -40^\circ C$ to $125^\circ C$	2	-	-	
Common Mode Rejection Ratio 2	CMR2	$V_{ICM} = -/+OPIN = 0V$ to 4V	70	90	-	dB
		$V_{ICM} = -/+OPIN = 0V$ to 4V, $T_a = -40^\circ C$ to $125^\circ C$	70	-	-	
Common Mode Input Voltage Range	$V_{ICM}$	CMR $\geq 70dB$ , -/+OPIN	0	-	4	V
		CMR $\geq 70dB$ , -/+OPIN, $T_a = -40^\circ C$ to $125^\circ C$	0	-	4	
Supply Voltage Rejection Ratio 2	SVR2	$V^+ = 2.2V$ to 5.5V	70	90	-	dB
		$V^+ = 2.2V$ to 5.5V, $T_a = -40^\circ C$ to $125^\circ C$	70	-	-	
Gain Bandwidth Product	GBW	$G_V = 40dB$ , $R_F = 100k\Omega$ , $R_L = 10k\Omega$ to 2.5V, $C_L = 20pF$ , $f = 100kHz$	-	1.3	-	MHz
Phase Margin	$\phi_M$	$G_V = 40dB$ , $R_F = 100k\Omega$ , $R_L = 10k\Omega$ to 2.5V, $C_L = 20pF$	-	60	-	deg
Gain Margin	$G_M$	$G_V = 40dB$ , $R_F = 100k\Omega$ , $R_L = 10k\Omega$ to 2.5V, $C_L = 20pF$	-	12	-	dB
Slew Rate	SR	$G_V = 0dB$ , $R_L = 10k\Omega$ to 2.5V, $C_L = 20pF$ , $V_{IN} = 3V_{PP}$	-	0.5	-	V/ $\mu s$

■ TYPICAL CHARACTERISTICS (General Characteristics/High Voltage Monitor)



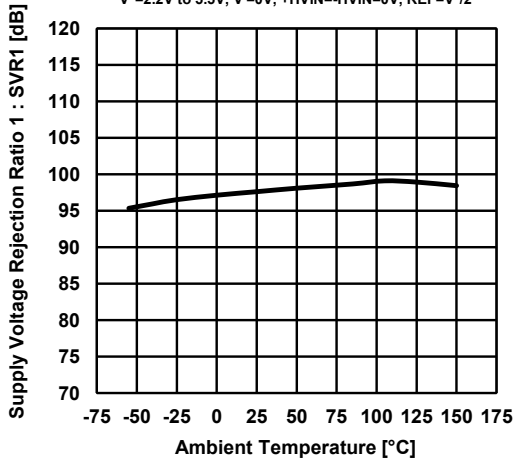
■ TYPICAL CHARACTERISTICS (General Characteristics /High Voltage Monitor)



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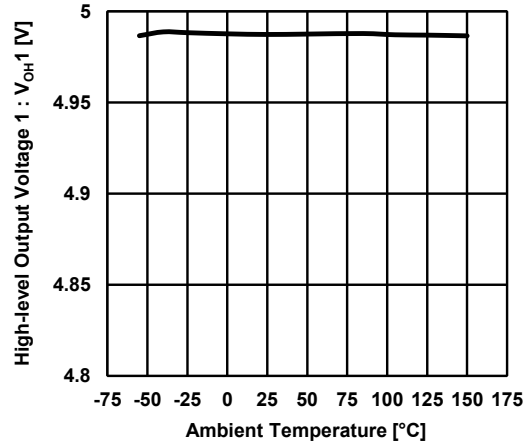
Supply Voltage Rejection Ratio 1 vs. Temperature  
(Common to each ver)

$V^+=2.2V$  to  $5.5V$ ,  $V=0V$ ,  $+HVIN=-HVIN=0V$ ,  $REF=V^+/2$



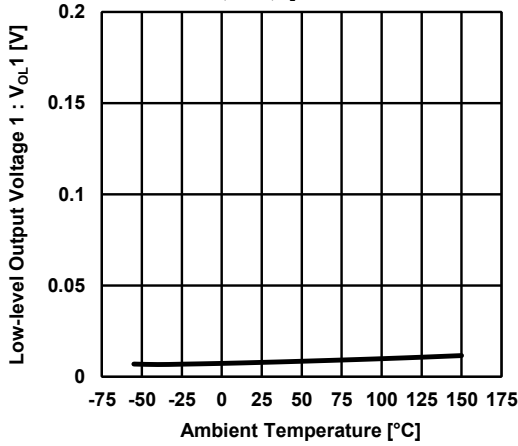
High-level Output Voltage 1 vs. Temperature  
(Common to each ver)

$V^+=5V$ ,  $V=0V$ ,  $R_L=10k\Omega$  to  $2.5V$



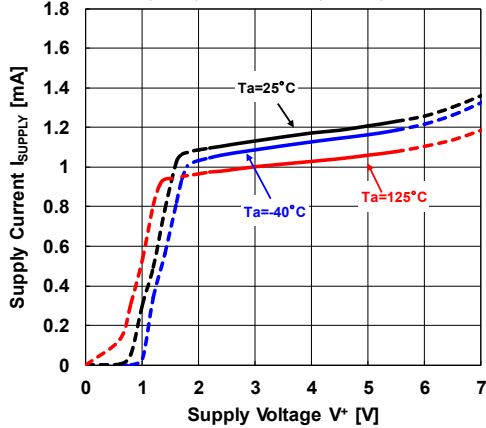
Low-level Output Voltage 1 vs. Temperature  
(Common to each ver)

$V^+=5V$ ,  $V=0V$ ,  $R_L=10k\Omega$  to  $2.5V$



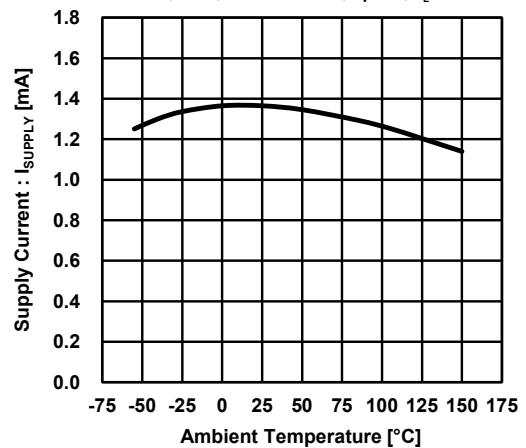
Supply Current vs. Supply Voltage  
(Common to each ver)

$V+=5V$ ,  $V=0V$ ,  $+HVIN=-HVIN=0V$ ,  $G_V=0dB$ ,  $R_L=OPEN$

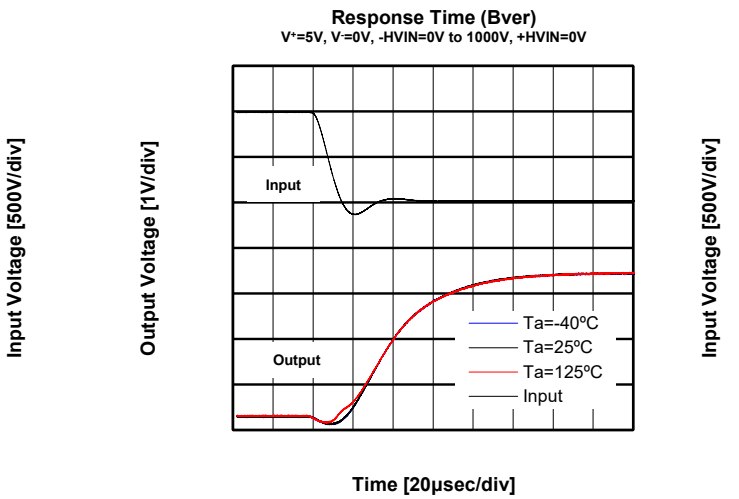
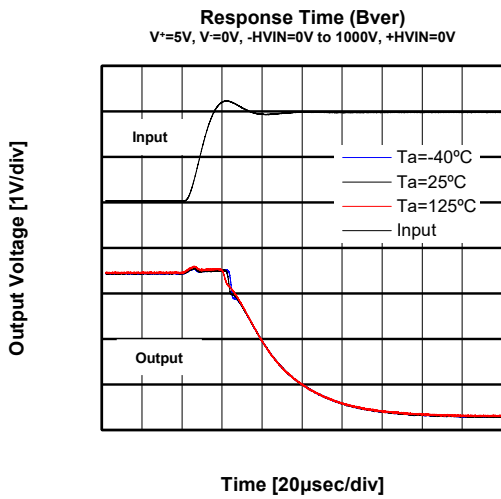
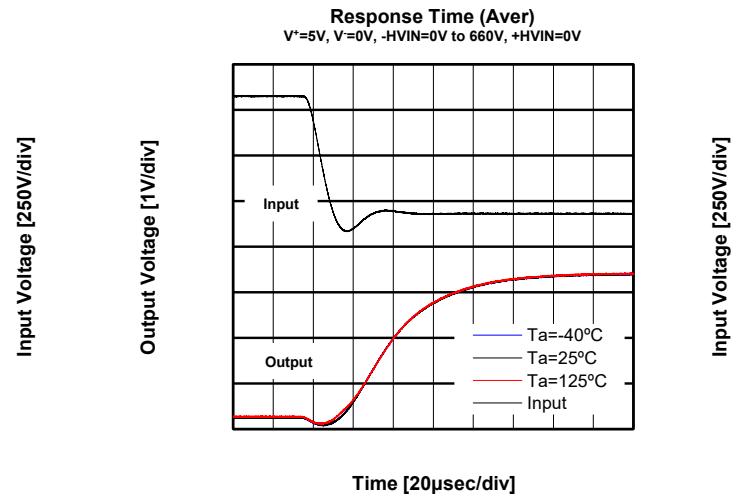
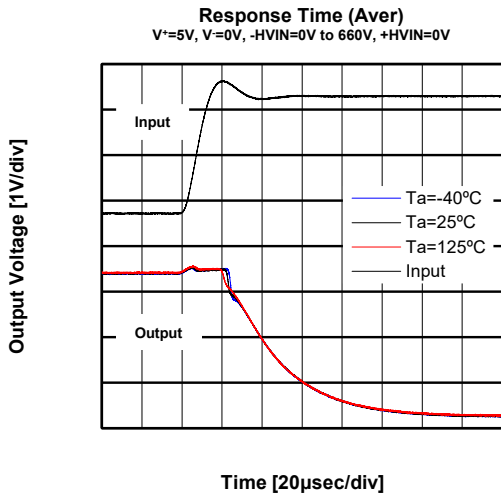


Supply Current vs. Temperature  
(Common to each ver)

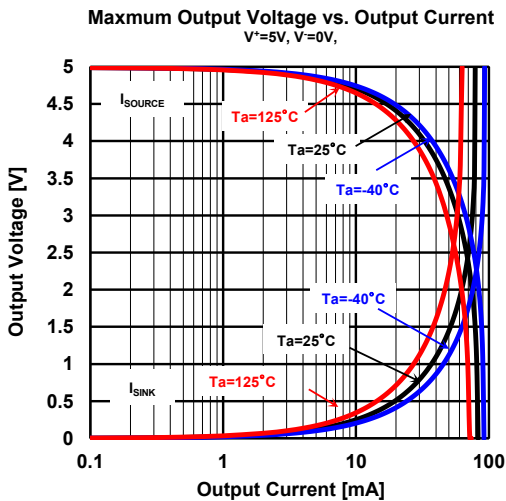
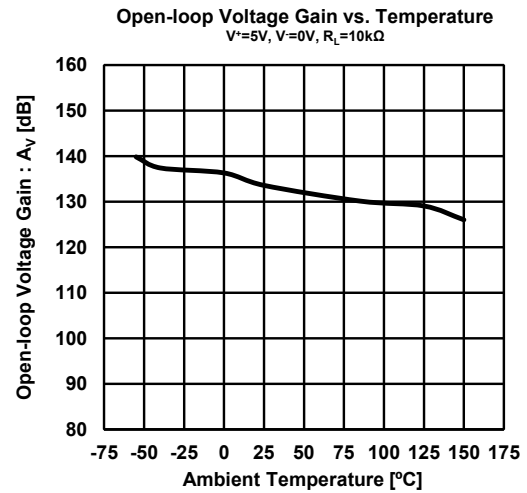
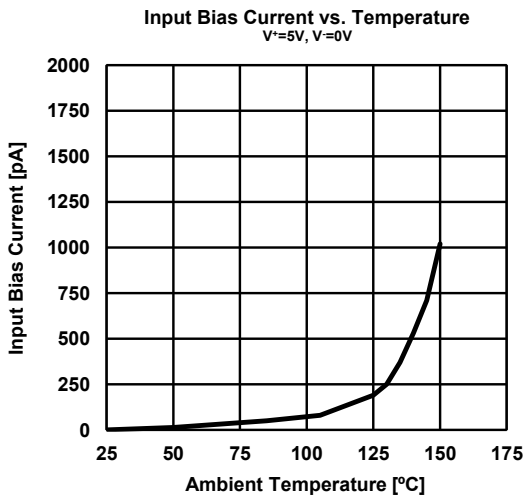
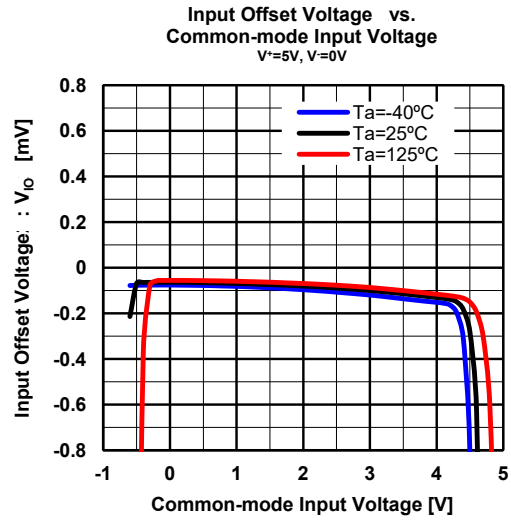
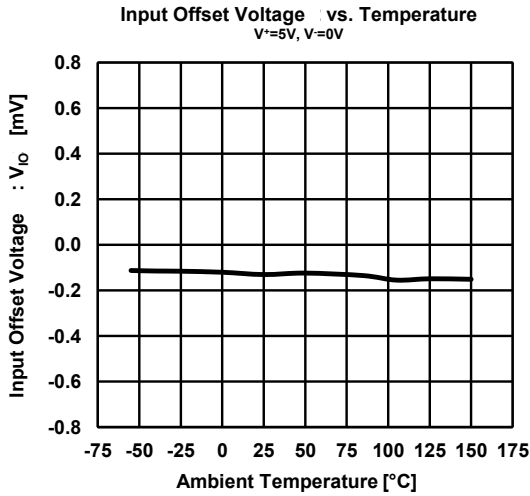
$V^+=5V$ ,  $V=0V$ ,  $+HVIN=-HVIN=0V$ ,  $G_V=0dB$ ,  $R_L=OPEN$



■ TYPICAL CHARACTERISTICS (General Characteristics High Voltage Monitor)

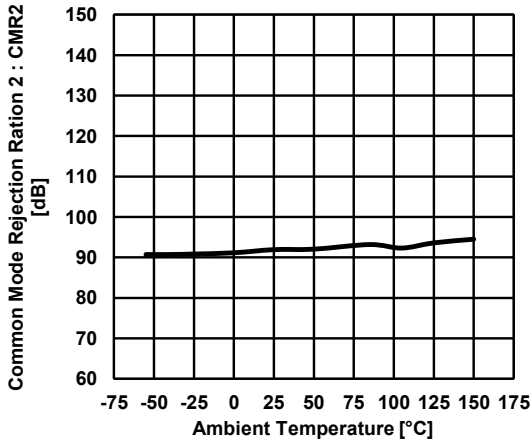


■ TYPICAL CHARACTERISTICS (Operational Amplifier)

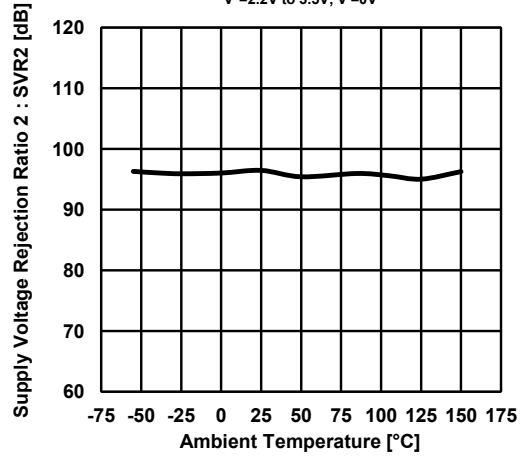


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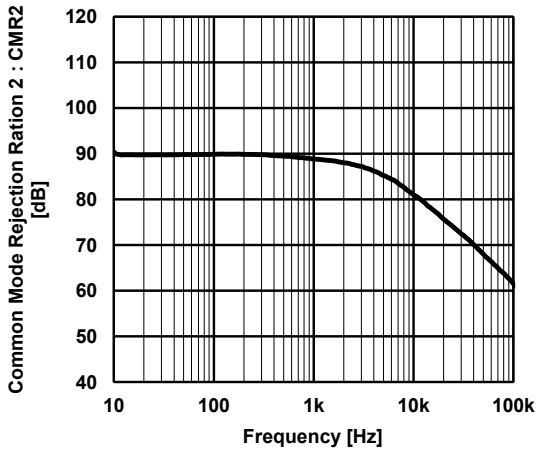
Common Mode Rejection Ratio 2 vs. Temperature  
 $V^+=5V, V^-=0V, +OPIN=0V$  to 4V



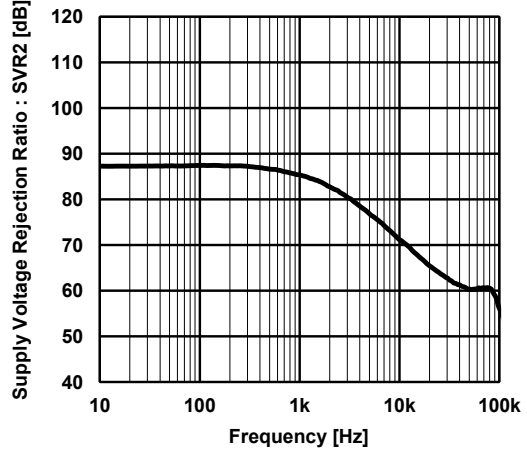
Supply Voltage Rejection Ratio 2 vs. Temperature  
 $V^+=2.2V$  to 5.5V,  $V^-=0V$



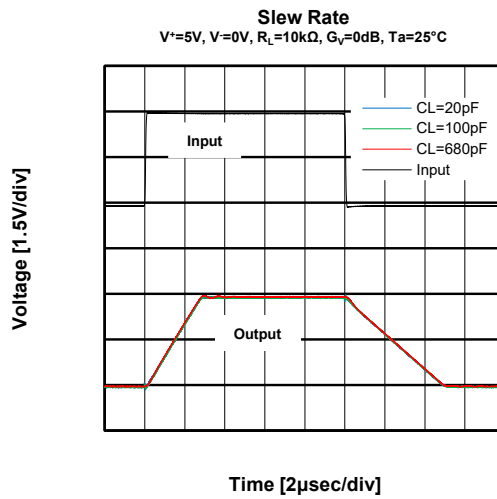
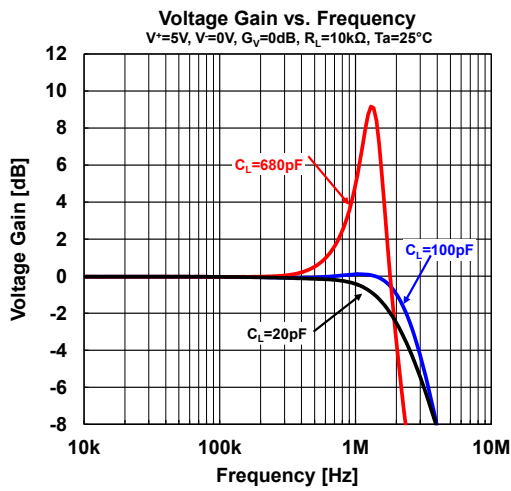
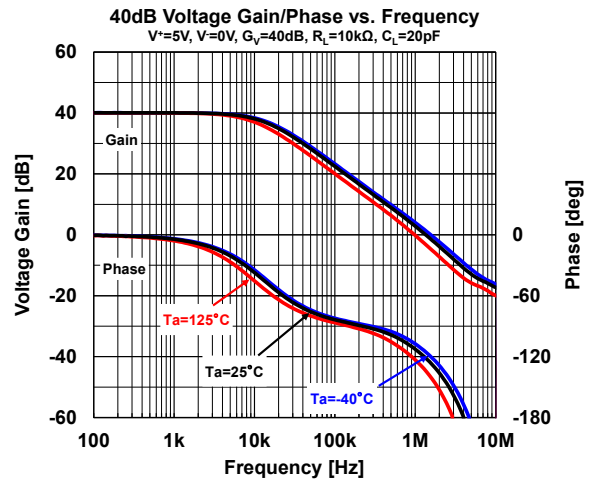
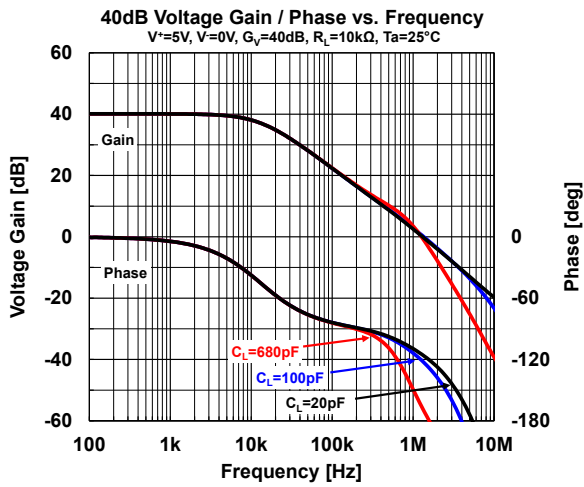
Common Mode Rejection Ratio 2 vs. Frequency  
 $V^+=5V, V^-=0V, V_{IN}=1V_{pp}, R_S=100\Omega, R_F=10k\Omega, T_a=25^\circ C$



Supply Voltage Rejection Ratio 2 vs. Frequency  
 $V^+=5V, V^-=0V, V_{IN}=1V_{pp}, R_S=100\Omega, R_F=10k\Omega, T_a=25^\circ C$



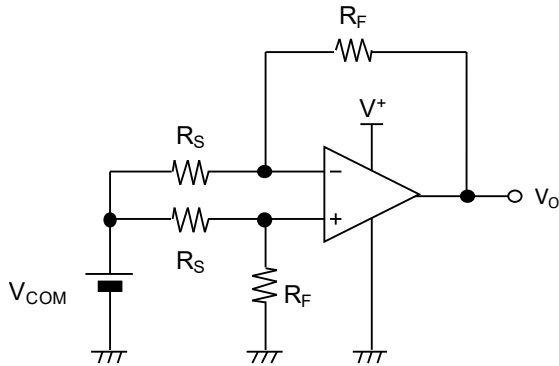
■ TYPICAL CHARACTERISTICS (Operational Amplifier)



■ TEST CIRCUITS

- $V_{IO}$ , CMR2, SVR2

$R_S = 50\Omega$ ,  $R_F = 50k\Omega$



$$V_{IO} = \frac{R_S}{(R_S + R_F)} \times (V_O - V_{COM})$$

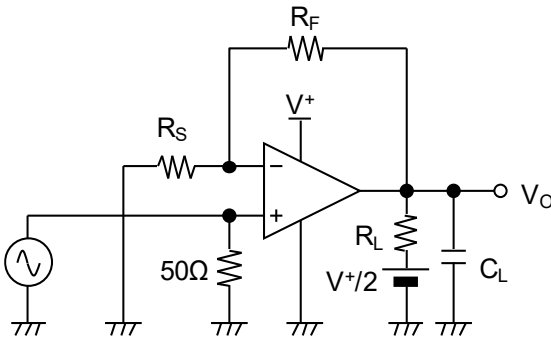
$$CMR2 = 20 \log \frac{\Delta V_{COM} \left(1 + \frac{R_F}{R_S}\right)}{\Delta V_O}$$

$$SVR2 = 20 \log \frac{\Delta V_S \left(1 + \frac{R_F}{R_S}\right)}{\Delta V_O}$$

$$V_S = V^+ - V^-$$

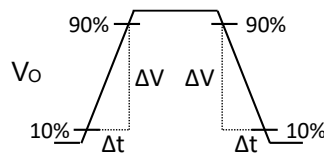
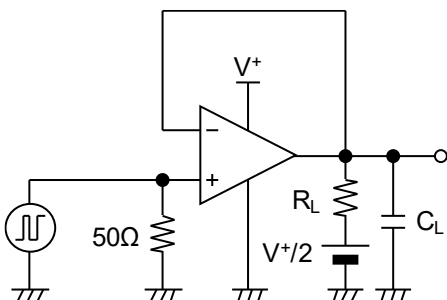
- GBW

$R_S = 1k\Omega$ ,  $R_F = 100k\Omega$



- SR

$C_L = 20pF$ ,  $R_L = 10k\Omega$



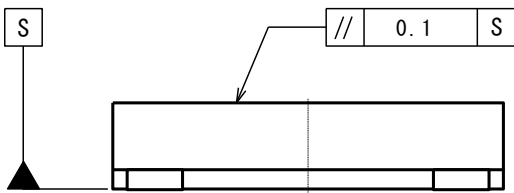
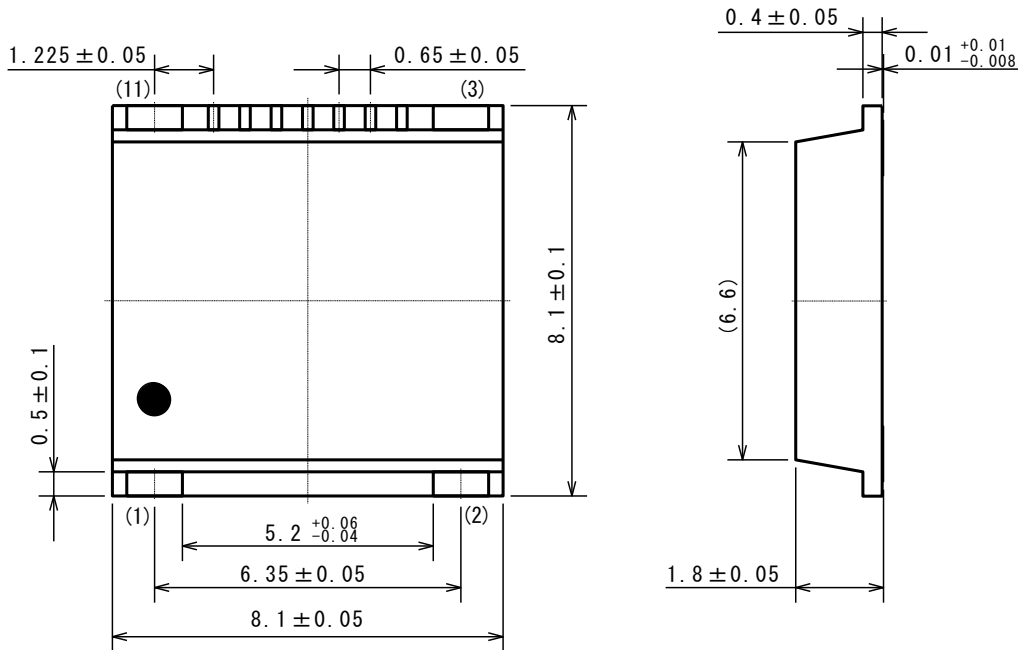
$$SR = \frac{\Delta V}{\Delta t}$$

**Note on using NJU7890**

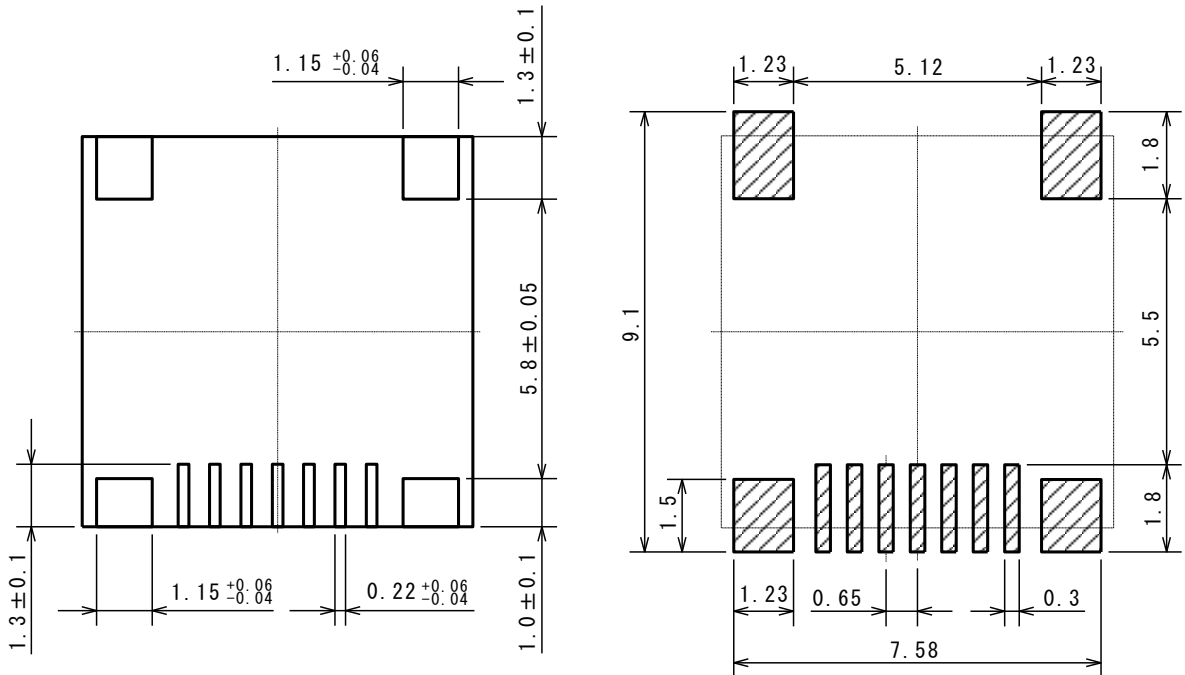
This part handles high voltage, therefore it needs sufficient consideration to avoid unforeseen critical failures. Please make sure that implement and verify fail-safe and/or redundant and secure design in customer own actual application to prevent personal injury, fire and social damage. The FMEA document of this part is a highly recommended reference for application design .

Unit: mm

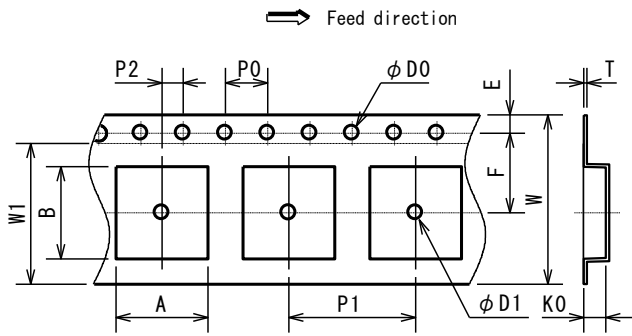
■ PACKAGE DIMENSIONS



■ EXAMPLE OF SOLDER PADS DIMENSIONS

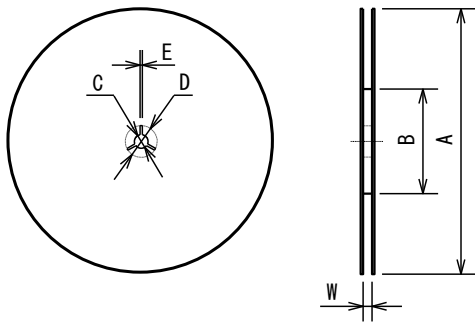


PACKING SPEC  
TAPING DIMENSIONS



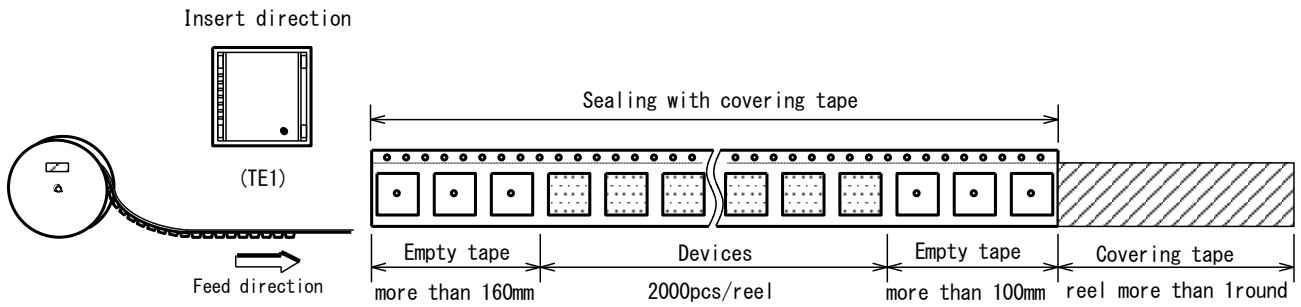
SYMBOL	DIMENSION	REMARKS
A	8.7±0.1	BOTTOM DIMENSION
B	8.7±0.1	BOTTOM DIMENSION
D0	1.5 <sup>+0.1</sup> <sub>0</sub>	
D1	1.5 <sup>+0.1</sup> <sub>0</sub>	
E	1.75±0.1	
F	7.5±0.1	
P0	4.0±0.1	
P1	12.0±0.1	
P2	2.0±0.1	
K0	2.1±0.1	
T	0.3±0.1	
W	16.0 <sup>+0.3</sup> <sub>-0.1</sub>	
W1	13.3±0.1	THICKNESS 0.1max

REEL DIMENSIONS

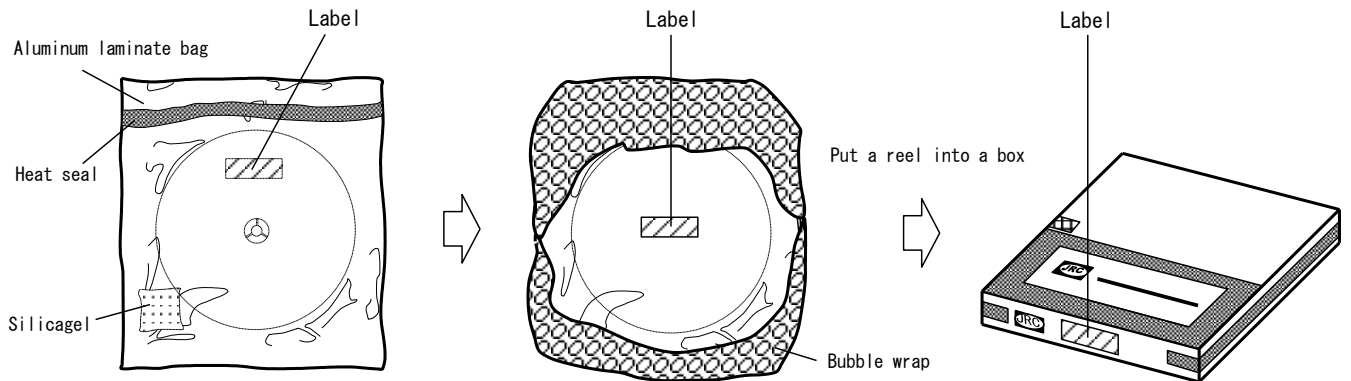


SYMBOL	DIMENSION
A	φ 330±2
B	φ 100±1
C	φ 13±0.2
D	21±0.8
E	2±0.5
W	17.5±1

TAPING STATE

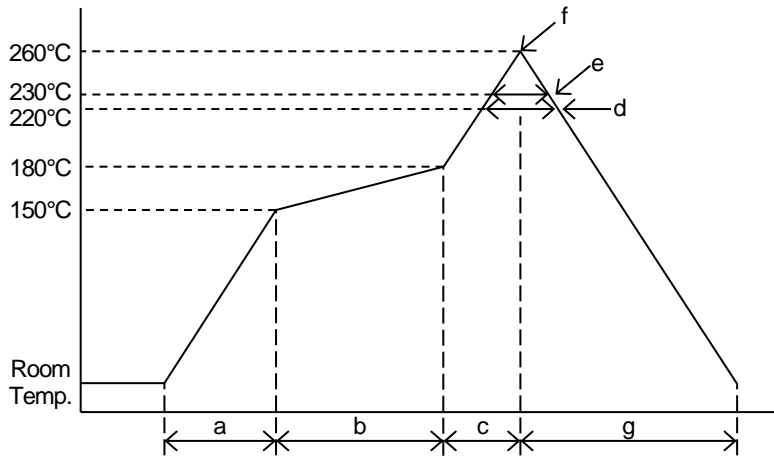


PACKING STATE



■ RECOMMENDED MOUNTING METHOD

INFRARED REFLOW SOLDERING PROFILE



a	Temperature ramping rate	1 to 4°C/s
b	Pre-heating temperature Pre-heating time	150 to 180°C 60 to 120s
c	Temperature ramp rate	1 to 4°C/s
d	220°C or higher time	shorter than 60s
e	230°C or higher time	shorter than 40s
f	Peak temperature	lower than 260°C
g	Temperature ramping rate	1 to 6°C/s

The temperature indicates at the surface of mold package.

■ REVISION HISTORY

DATE	REVISION	CHANGES
February 9, 2021	Ver.1.0	Initial release
June 29,2021	Ver.2.0	Corrected FEATURES and PACKAGE DIMENSIONS
October 1,2024	Ver.3.0	Company name and logo changed to Nisshinbo Microdevices Inc.

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  - Equipment Used in the Deep Sea
  - Power Generator Control Equipment (nuclear, steam, hydraulic, etc.)
  - Life Maintenance Medical Equipment
  - Fire Alarms / Intruder Detectors
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  - Various Safety Devices
  - Traffic control system
  - Combustion equipment

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8. **Quality Warranty**
  - 8-1. **Quality Warranty Period**  
In the case of a product purchased through an authorized distributor or directly from us, the warranty period for this product shall be one (1) year after delivery to your company. For defective products that occurred during this period, we will take the quality warranty measures described in section 8-2. However, if there is an agreement on the warranty period in the basic transaction agreement, quality assurance agreement, delivery specifications, etc., it shall be followed.
  - 8-2. **Quality Warranty Remedies**  
When it has been proved defective due to manufacturing factors as a result of defect analysis by us, we will either deliver a substitute for the defective product or refund the purchase price of the defective product.  
Note that such delivery or refund is sole and exclusive remedies to your company for the defective product.
  - 8-3. **Remedies after Quality Warranty Period**  
With respect to any defect of this product found after the quality warranty period, the defect will be analyzed by us. On the basis of the defect analysis results, the scope and amounts of damage shall be determined by mutual agreement of both parties. Then we will deal with upper limit in Section 8-2. This provision is not intended to limit any legal rights of your company.
9. Anti-radiation design is not implemented in the products described in this document.
10. The X-ray exposure can influence functions and characteristics of the products. Confirm the product functions and characteristics in the evaluation stage.
11. WLCSP products should be used in light shielded environments. The light exposure can influence functions and characteristics of the products under operation or storage.
12. Warning for handling Gallium and Arsenic (GaAs) products (Applying to GaAs MMIC, Photo Reflector). These products use Gallium (Ga) and Arsenic (As) which are specified as poisonous chemicals by law. For the prevention of a hazard, do not burn, destroy, or process chemically to make them as gas or power. When the product is disposed of, please follow the related regulation and do not mix this with general industrial waste or household waste.
13. Please contact our sales representatives should you have any questions or comments concerning the products or the technical information.



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